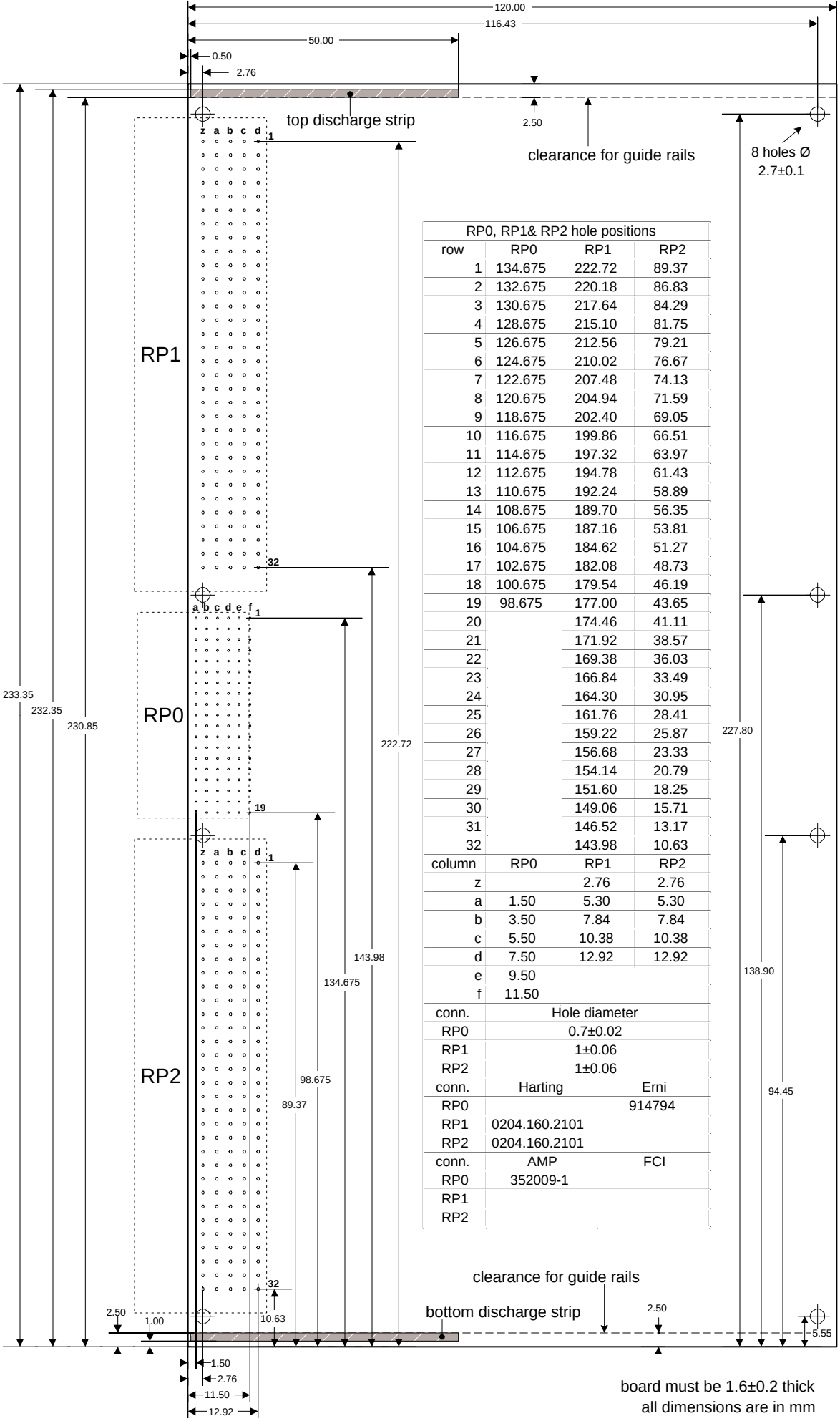

RP0, RP1& RP2 hole positions			
row	RP0	RP1	RP2
1	134.675	222.72	89.37
2	132.675	220.18	86.83
3	130.675	217.64	84.29
4	128.675	215.10	81.75
5	126.675	212.56	79.21
6	124.675	210.02	76.67
7	122.675	207.48	74.13
8	120.675	204.94	71.59
9	118.675	202.40	69.05
10	116.675	199.86	66.51
11	114.675	197.32	63.97
12	112.675	194.78	61.43
13	110.675	192.24	58.89
14	108.675	189.70	56.35
15	106.675	187.16	53.81
16	104.675	184.62	51.27
17	102.675	182.08	48.73
18	100.675	179.54	46.19
19	98.675	177.00	43.65
20		174.46	41.11
21		171.92	38.57
22		169.38	36.03
23		166.84	33.49
24		164.30	30.95
25		161.76	28.41
26		159.22	25.87
27		156.68	23.33
28		154.14	20.79
29		151.60	18.25
30		149.06	15.71
31		146.52	13.17
32		143.98	10.63
column	RP0	RP1	RP2
z		2.76	2.76
a	1.50	5.30	5.30
b	3.50	7.84	7.84
c	5.50	10.38	10.38
d	7.50	12.92	12.92
e	9.50		
f	11.50		
conn.	Hole diameter		
RP0	0.7±0.02		
RP1	1±0.06		
RP2	1±0.06		
conn.	Harting	Erni	
RP0		914794	
RP1	0204.160.2101		
RP2	0204.160.2101		
conn.	AMP	FCI	
RP0	352009-1		
RP1			
RP2			

board must be 1.6±0.2 thick
all dimensions are in mm
extracted from IEEE 1101.1, IEEE 1101.10 & VITA 1.1-199x

VME64x 6Ux120mm TRANSITION MODULE (SR 08/09/97)